



Intel® Server System MCB2224BPAF3R

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Ordering and Compliance

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Technical Documentation

Essentials

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Product Collection	Intel® Data Center Blocks for Cloud (Intel® DCB for Cloud)
Code Name	Products formerly Buchanan Pass
Launch Date ?	Q2'19
Status	Launched
Expected Discontinuance ?	2023
ISV Certification ?	Microsoft Windows Server 2019* Software-Defined Data Center (SDDC) Premium
Rack Rails Included	Yes
Compatible Product Series	2nd Generation Intel® Xeon® Scalable Processors
TDP ?	125 W
System Board	Intel® Compute Module HNS2600BPS24R
Target Market	Cloud/Datacenter

Included Items

(1) 2U Chassis (24x2.5") H2224XXLR3
 (4) Compute Module (w/TPM 2.0, 2x10GbE SFP+ & 1GbE, RDMA) HNS2600BPS24R
 (8) Intel® Xeon Gold 5218R processor (20 Cores, 2.1Ghz, 125W) CD8069504446300
 (4) Intel® Solid State Drive (SSD) DC P4101 256GB (M.2, 80mm NVMe) SSDPEKKA256G801
 (24) Intel® Solid State Drive (SSD) D3 S4510 1.92TB (2.5" U.2 SATA) SSDSC2KB019T801
 (4) Bridge Board - 12G, IT mode only AHWPBGB24
 (4) Intel® Remote Management Module Lite 2 accessory key AXXRMM4LITE2
 (32) 32GB Micron® DDR4 RDIMM, 288-pin, 2666MHz (8 DIMMs per node/32 DIMMs per system)
 (2) Power cable FPWRCABLENA (Only for systems shipped to USA & Canada)

Supplemental Information

Description	Intel® Data Center Blocks for Microsoft® Azure® Stack HCI includes Server Board, Chassis, Processor, Solid State Drives and third-party memory, optimized for Storage Spaces Direct and built with Microsoft® Windows® Server 2019 certified ingredients
Additional Information	View now

Memory & Storage

Storage Profile ?	All-Flash Storage Profile
Included Memory ?	256GB(node)/1024GB(system) DDR4 RAM Raw Memory
Included Storage	46.08TB Raw Storage (4x 0.25TB boot device, 46.08TB Capacity Tier)

Ordering and spec information

Intel® Server System MCB2224BPAF3R, Single

MM#	99A3JR
OrderingCode	MCB2224BPAF3R

Trade compliance information

ECC	Varies By Product
PCode	Varies By Product
HTS	Varies By Product

More support options for Intel® Server System MCB2224BPAF3R

 Product Support	 Downloads and Software	 Support Community	 Warranty and Replacement
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Refer to Datasheet for formal definitions of product properties and features.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

*Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

